

LM148, LM248, LM348 QUADRUPLE OPERATIONAL AMPLIFIERS

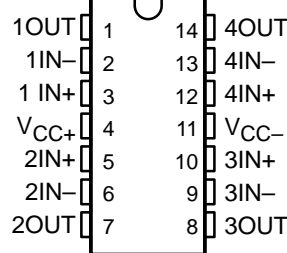
SLOS058C – OCTOBER 1979 – REVISED DECEMBER 2002

- μ A741 Operating Characteristics
- Low Supply-Current Drain . . . 0.6 mA Typ (per amplifier)
- Low Input Offset Voltage
- Low Input Offset Current
- Class AB Output Stage
- Input/Output Overload Protection
- Designed to Be Interchangeable With Industry Standard LM148, LM248, and LM348

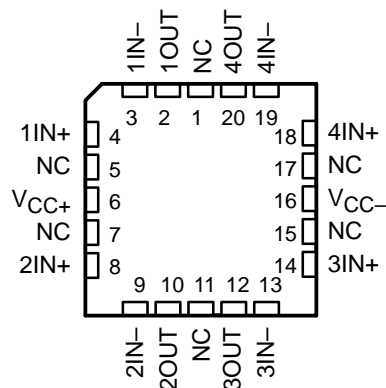
description/ordering information

The LM148, LM248, and LM348 are quadruple, independent, high-gain, internally compensated operational amplifiers designed to have operating characteristics similar to the μ A741. These amplifiers exhibit low supply-current drain and input bias and offset currents that are much less than those of the μ A741.

LM148 . . . J PACKAGE
LM248 . . . D OR N PACKAGE
LM348 . . . D, N, OR NS PACKAGE
(TOP VIEW)



LM148 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T_A	V_{IOmax} AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	6 mV	PDIP (N)	Tube of 25	LM348N	LM348N
		SOIC (D)	Tube of 50	LM348D	LM348
			Reel of 2500	LM348DR	
		SOP (NS)	Reel of 2000	LM348NSR	LM348
–25°C to 85°C	6 mV	PDIP (N)	Tube of 25	LM248N	LM248N
		SOIC (D)	Tube of 50	LM248D	LM248
			Reel of 2500	LM248DR	
		CDIP (J)	Tube of 25	LM148J	LM148J
–55°C to 125°C	5 mV	LCCC (FK)	Tube of 50	LM148FK	LM148FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2002, Texas Instruments Incorporated
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

LM148, LM248, LM348 QUADRUPLE OPERATIONAL AMPLIFIERS

SLOS058C – OCTOBER 1979 – REVISED DECEMBER 2002

symbol (each amplifier)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC+} (see Note 1):	LM148	22 V
	LM248, LM348	18 V
Supply voltage, V_{CC-} (see Note 1):	LM148	-22 V
	LM248, LM348	-18 V
Differential input voltage, V_{ID} (see Note 2):	LM148	44 V
	LM248, LM348	36 V
Input voltage, V_I (either input, see Notes 1 and 3):	LM148	-22 V
	LM248, LM348	-18 V
Duration of output short circuit (see Note 4)		Unlimited
Operating virtual junction temperature, T_J		150°C
Package thermal impedance, θ_{JA} (see Notes 5 and 6):	D package	86°C/W
	N package	80°C/W
	NS package	76°C/W
Package thermal impedance, θ_{JC} (see Notes 7 and 8):	FK package	5.61°C/W
	J package	15.05°C/W
Case temperature for 60 seconds: FK package		260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: J package		300°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: D, N, or NS package		260°C
Storage temperature range, T_{stg}		-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 2. Differential voltages are at $IN+$ with respect to $IN-$.
 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or the value specified in the table, whichever is less.
 4. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{CC+}	4	18	V
Supply voltage, V_{CC-}	-4	-18	V



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		LM148			LM248			LM348			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0$	25°C	1	5		1	6		1	6	mV	
		Full range		6		7.5		7.5				
I_{IO} Input offset current	$V_O = 0$	25°C	4	25		4	50		4	50	nA	
		Full range		75		125		100				
I_{IB} Input bias current	$V_O = 0$	25°C	30	100		30	200		30	200	nA	
		Full range		325		500		400				
V_{ICR} Common-mode input voltage range		Full range	±12			±12			±12		V	
V_{OM} Maximum peak output voltage swing	$R_L = 10\text{ k}\Omega$	25°C	±12		±13	±12		±13	±12		V	
		Full range	±12			±12			±12			
		25°C	±10		±12	±10		±12	±10			
		Full range	±10			±10			±10			
A_{VD} Large-signal differential voltage amplification	$V_O = \pm 10\text{ V}$, $R_L = \geq 2\text{ k}\Omega$	25°C	50	160		25	160		25	160	V/mV	
		Full range	25			15			15			
r_i Input resistance‡		25°C	0.8	2.5		0.8	2.5		0.8	2.5	MΩ	
B_1 Unity-gain bandwidth	$A_{VD} = 1$	25°C	1			1			1		MHz	
ϕ_m Phase margin	$A_{VD} = 1$	25°C	60°			60°			60°			
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$, $V_O = 0$	25°C	70	90		70	90		70	90	dB	
		Full range	70			70			70			
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC\pm} = \pm 9\text{ V to } \pm 15\text{ V}$, $V_O = 0$	25°C	77	96		77	96		77	96	dB	
		Full range	77			77			77			
I_{OS} Short-circuit output current		25°C	±25			±25			±25		mA	
I_{CC} Supply current (four amplifiers)	No load	$V_O = 0$				2.4		4.5	2.4		4.5	mA
		25°C	2.4		3.6							
V_{O1}/V_{O2} Crosstalk attenuation	$f = 1\text{ Hz to } 20\text{ kHz}$	25°C	120			120			120		dB	

† All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range for T_A is -55°C to 125°C for LM148, -25°C to 85°C for LM248, and 0°C to 70°C for LM348.

‡ This parameter is not production tested.

LM148, LM248, LM348 QUADRUPLE OPERATIONAL AMPLIFIERS

SLOS058C – OCTOBER 1979 – REVISED FEBRUARY 2002

operating characteristics, $V_{CC\pm} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR Slew rate at unity gain	$R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$, See Figure 1		0.5		$\text{V}/\mu\text{s}$

PARAMETER MEASUREMENT INFORMATION

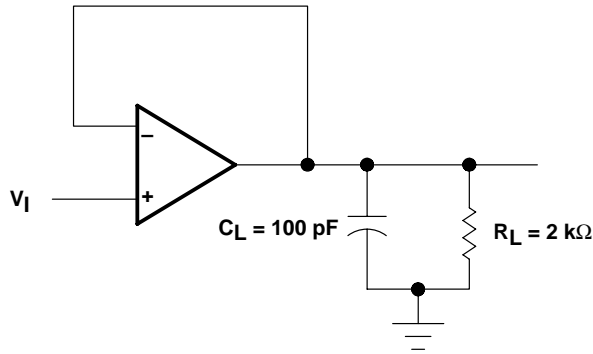


Figure 1. Unity-Gain Amplifier

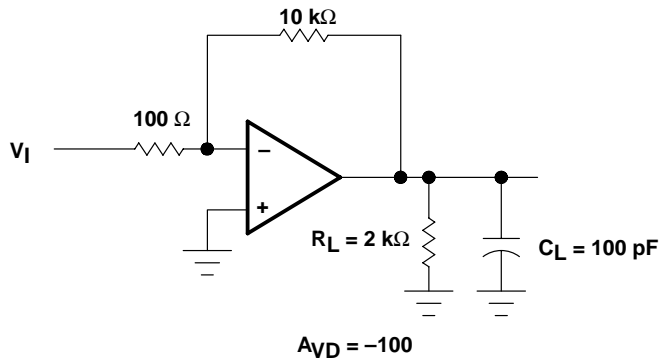


Figure 2. Inverting Amplifier

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LM148FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
LM148J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
LM148JB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
LM248D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM248NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM348D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM348NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM348NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM248DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

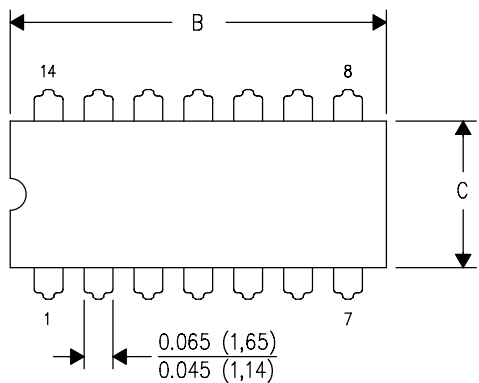

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM248DR	SOIC	D	14	2500	346.0	346.0	33.0
LM348DR	SOIC	D	14	2500	346.0	346.0	33.0
LM348DR	SOIC	D	14	2500	333.2	345.9	28.6
LM348NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

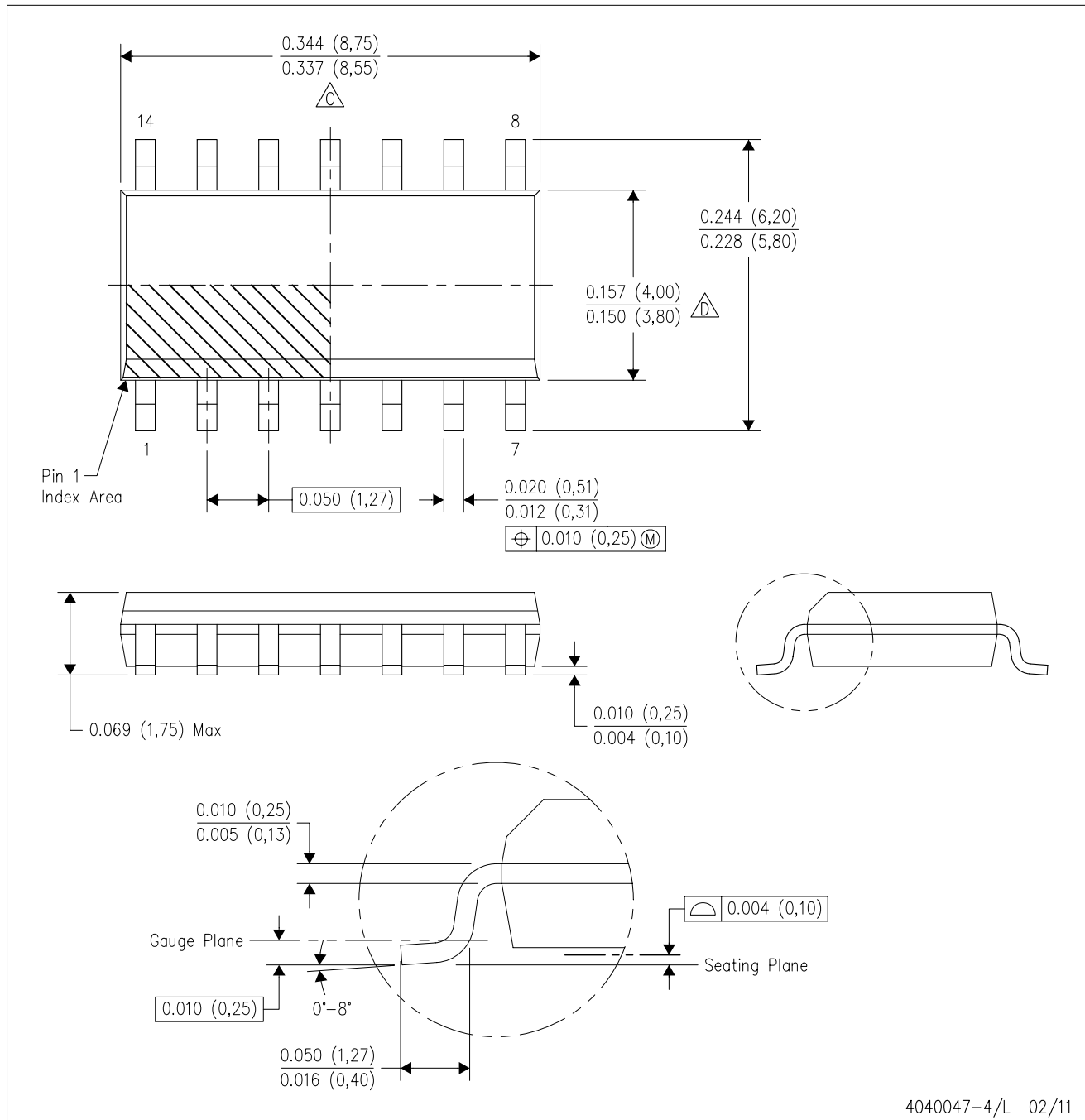
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

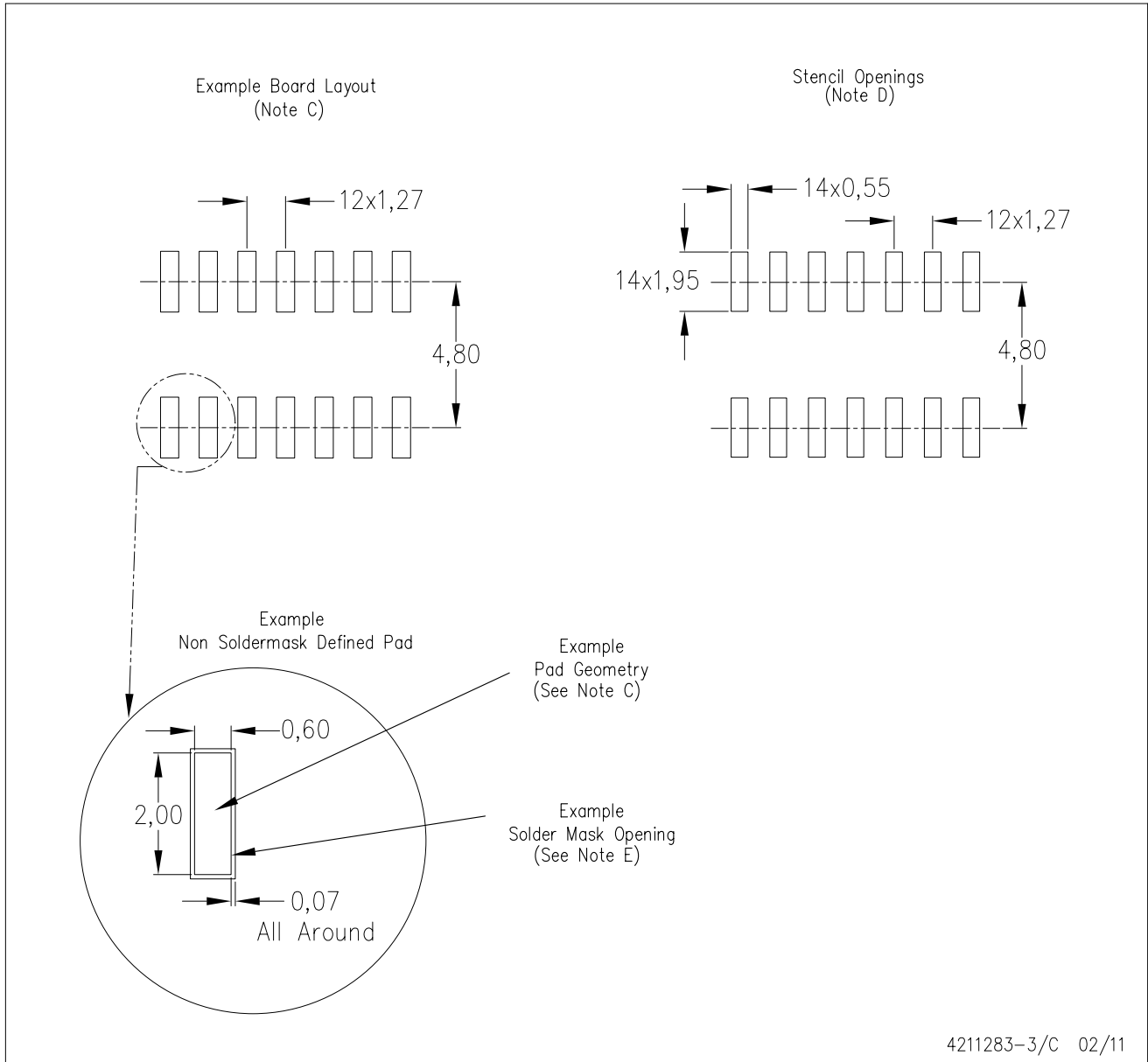
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video
Wireless	www.ti.com/wireless-apps

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated